



Your Trusted Partner in Semiconductor Testing

TWSE

6515

Investor Presentation

2025.09.16

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Company Information



■ Founded

2001 / 4 / 10

■ Business Operation

Design, manufacture, sale and service of test interface products

■ Chairman & CEO

Mark Wang

■ Capital Stock

NTD 360,491,820

■ Employees

1006

■ Registered Address

No.68, Chuangyi S. Rd, Nanzi Dist. Kaohsiung City, Taiwan

Agenda



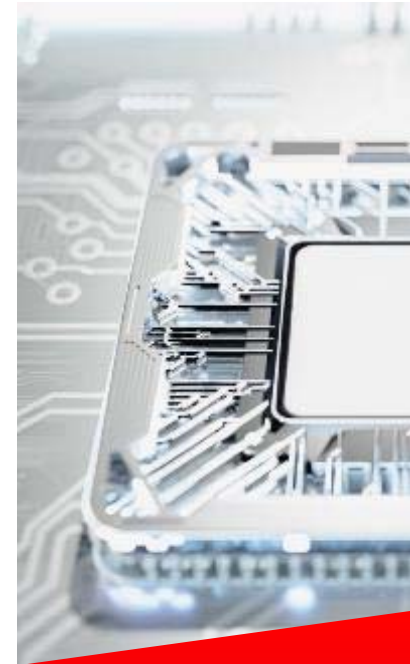
**Global
Presence**



**Industry
Trend**



**Financial
Performance**

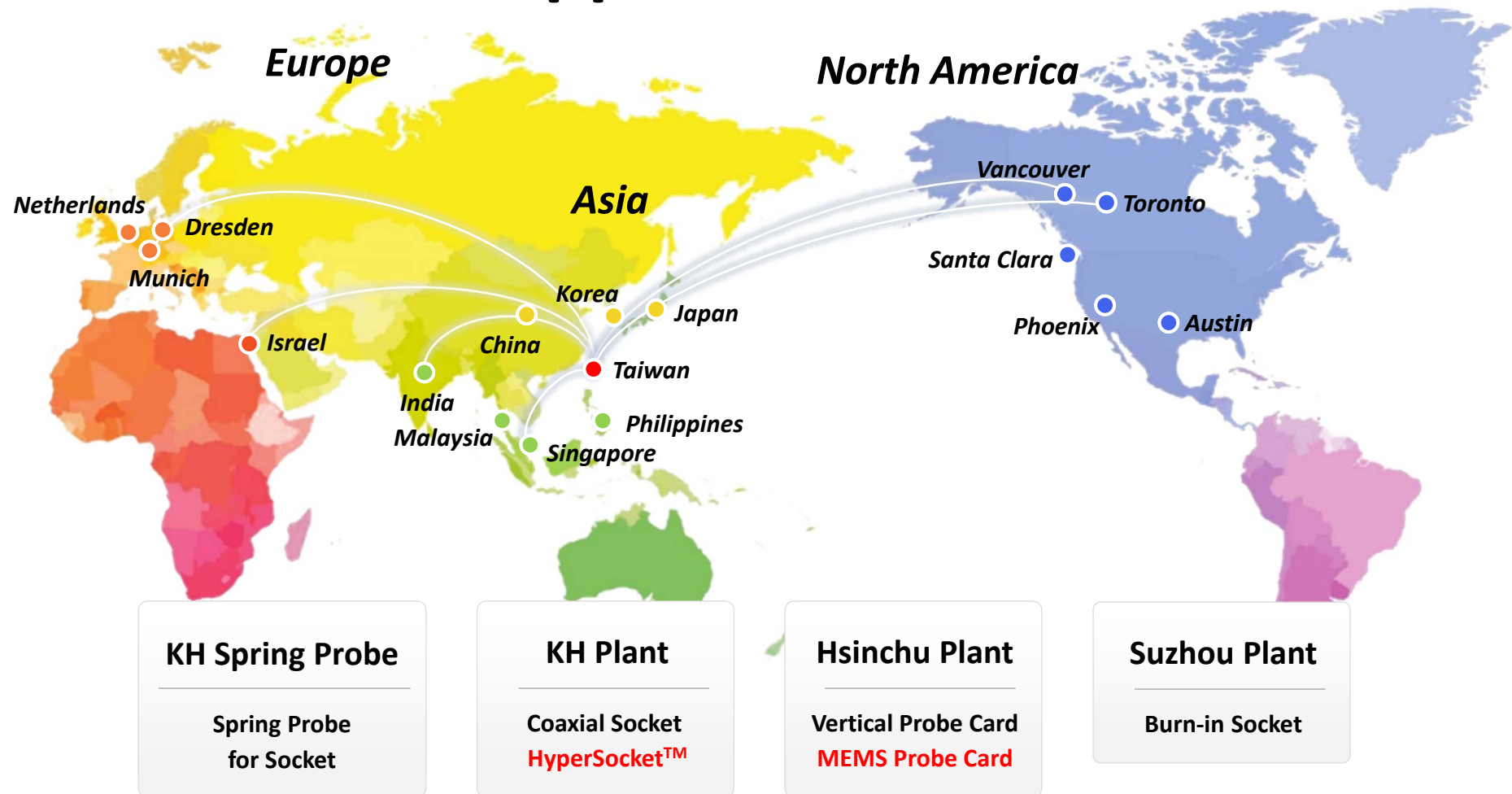


**R&D
Innovation**



Global Presence

Global Service & Support Network

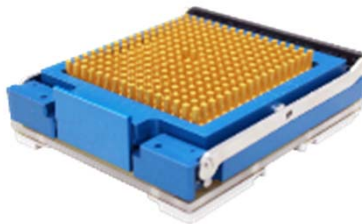


Semiconductor Test Interface Leadership

2024

Test and Burn-in Socket
Ranking

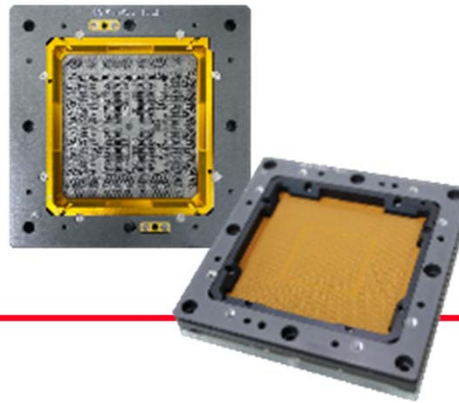
02



2024

Test Socket Ranking

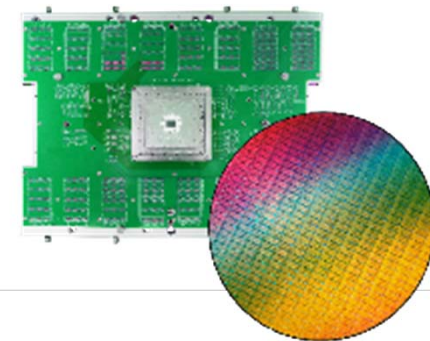
01



2024

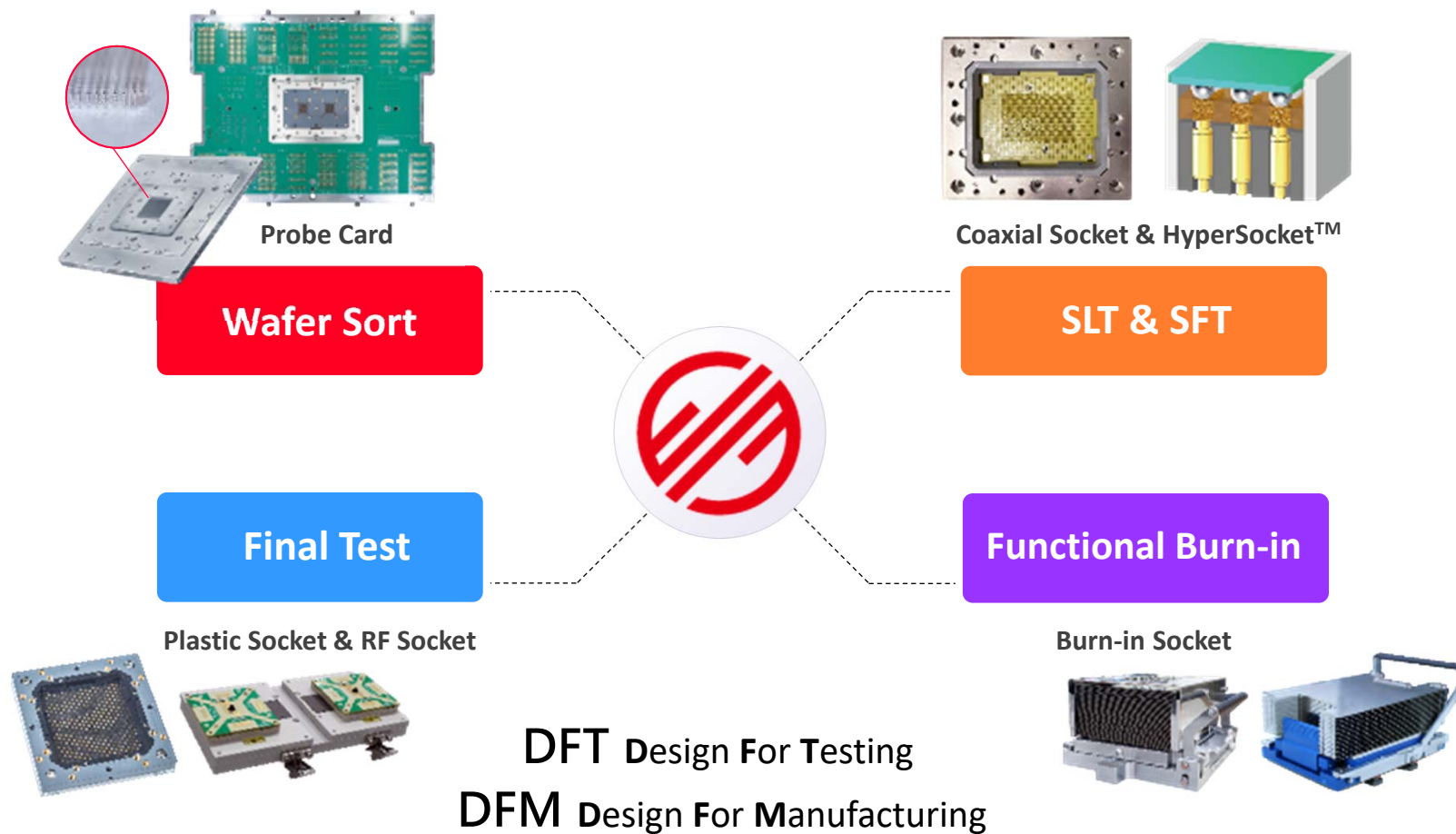
Probe Card Ranking

18



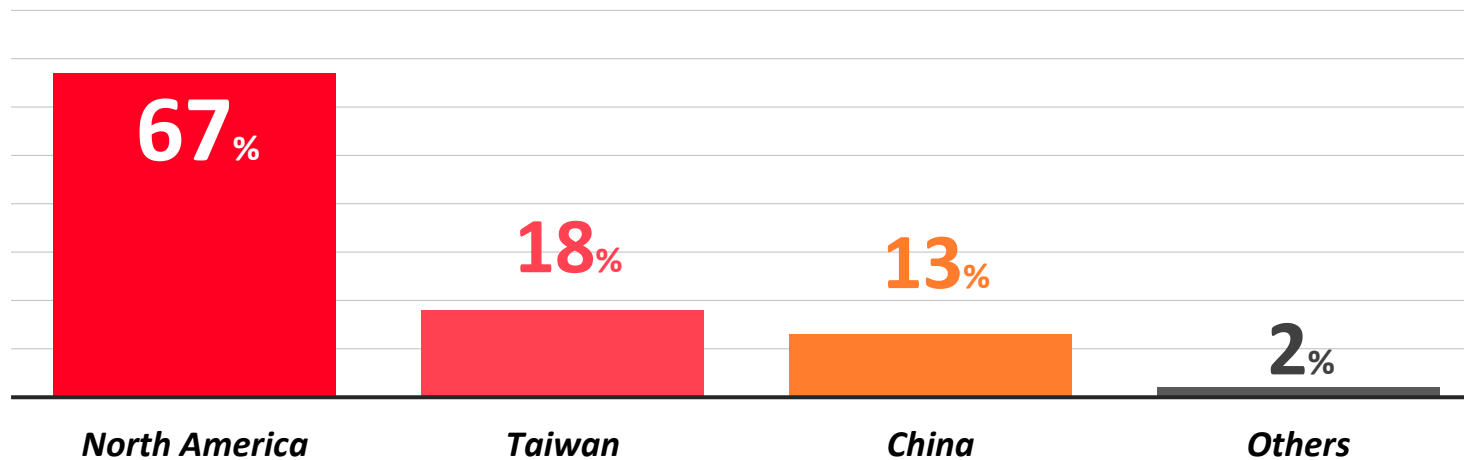
Source : Yole Intelligence, 2025/04

Total Solution for Semiconductor Test



Worldwide Customer

(1H 2025)



89% Top10 Customers

■ AI ■ AP
■ HPC ■ CPU
■ ASIC ■ GPU

200+ Active Customers

■ IC Design ■ IDM
■ CSP ■ OSAT
■ Foundry

Bolstered by Advanced Technology

(1H 2025)

Mature Node **13%**

Advanced Node **87%**
7nm (or equivalent node) and below

Automotive



Networking



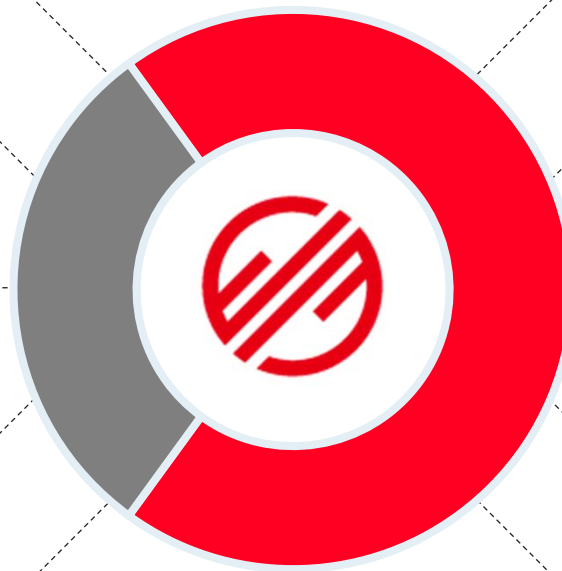
IoT



DTV & STB



NAND Flash



AI



HPC



GPU



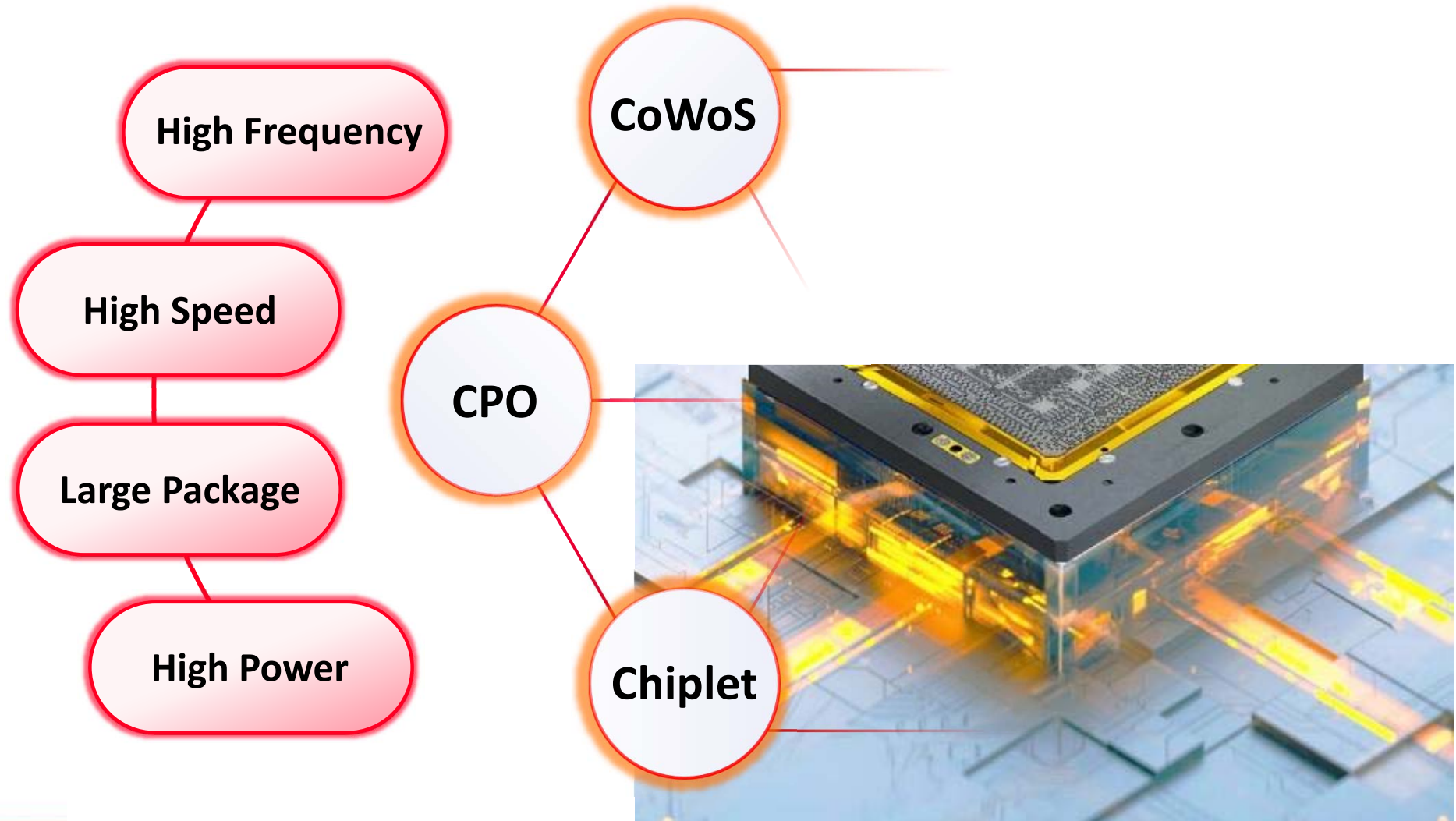
CPU



Smart Phone



High Performance Testing Driven by Advanced Packaging





Industry Trend

Driving Force for AI



Greater Importance on Chip Probing

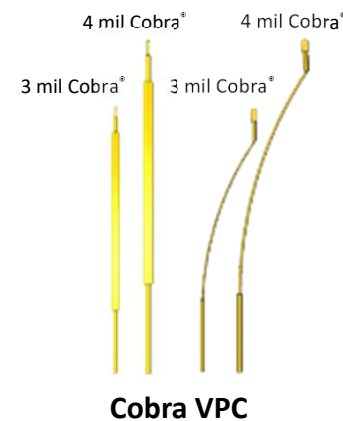
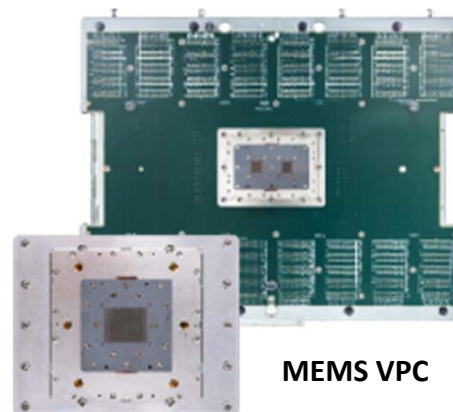
From the Shadows to the Spotlight

K.G.D Close to Known Good Die

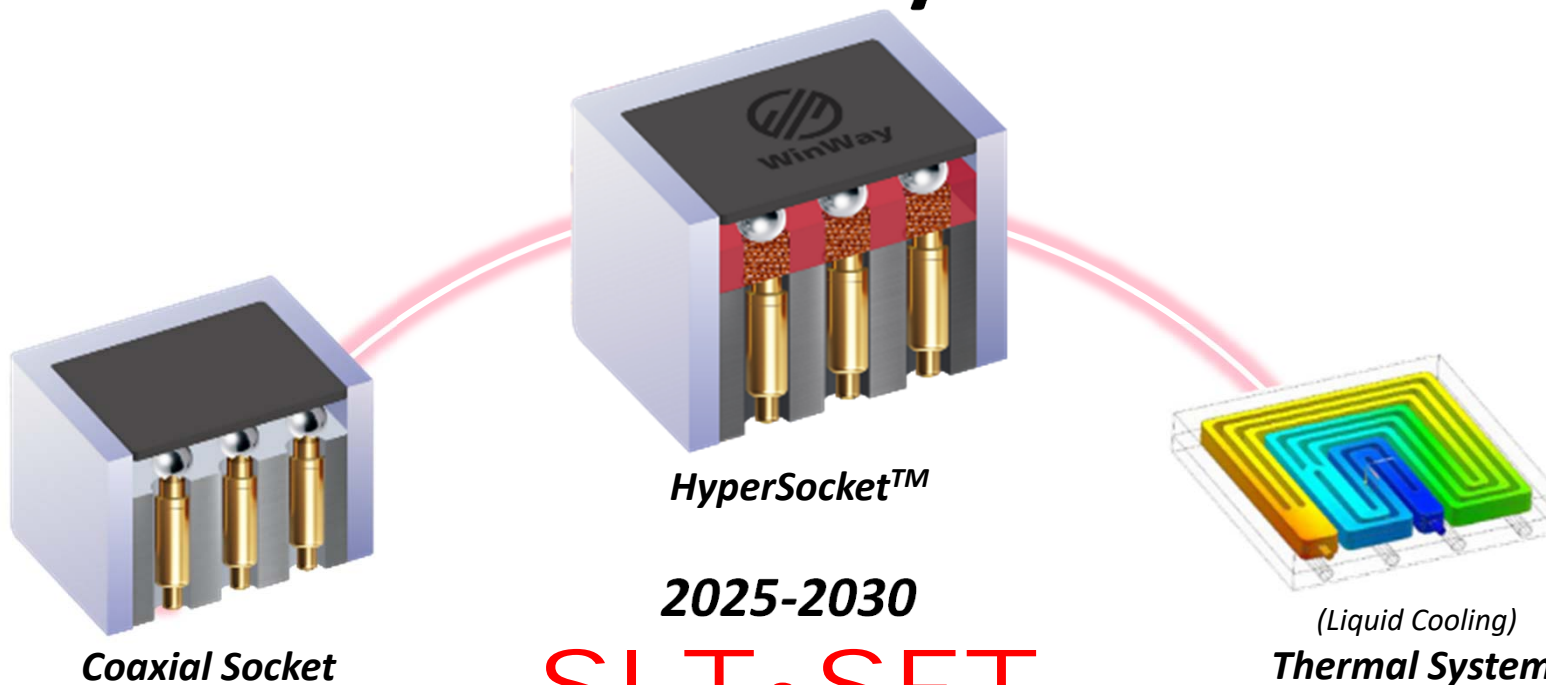
CoWoS

CPO

Chiplet



Accelerated SLT Demand Driven by AI



More than
Greater than
industry growth

15%

Source : WinWay 2025

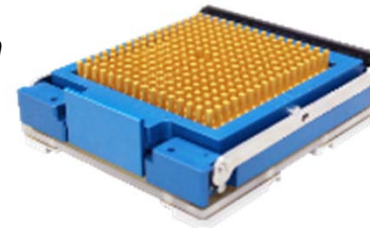
Emerging Trend Toward Functional Burn-In



Functional Burn-in
AI & HPC



Mass Production
Burn-in
Automotive



Reliability
Burn-in
For all IC testing

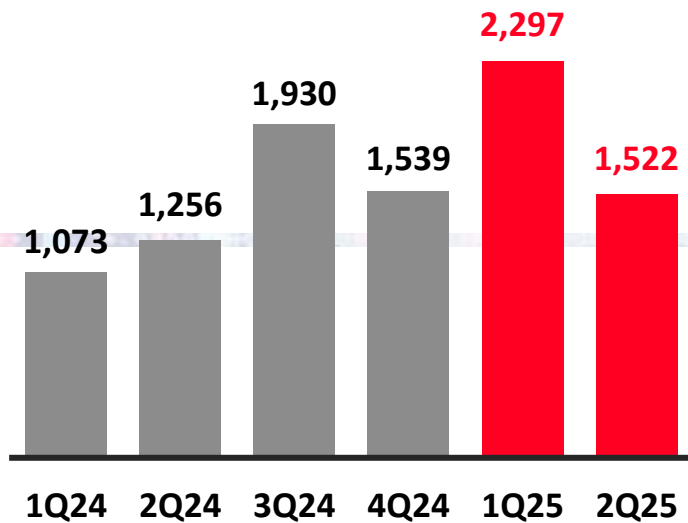




Financial Performance

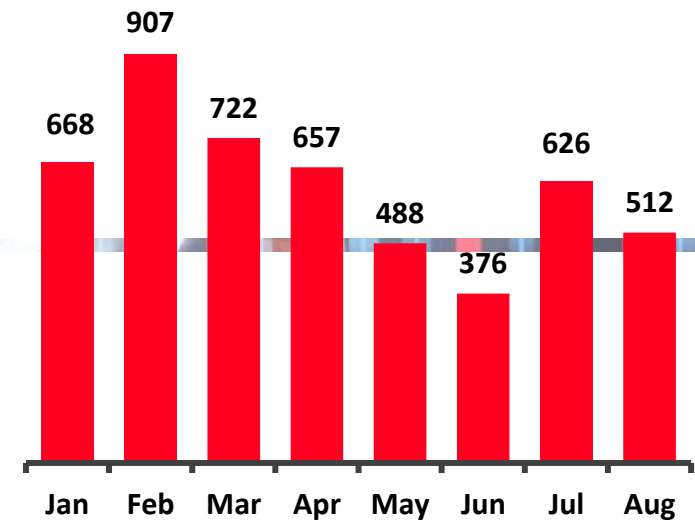
Revenue Trend

QUARTERLY REVENUE
(NTD MILLION)



YoY	6%	24%	96%	129%	114%	21%
QoQ	59%	17%	54%	-20%	49%	-34%

MONTHLY REVENUE
(NTD MILLION)



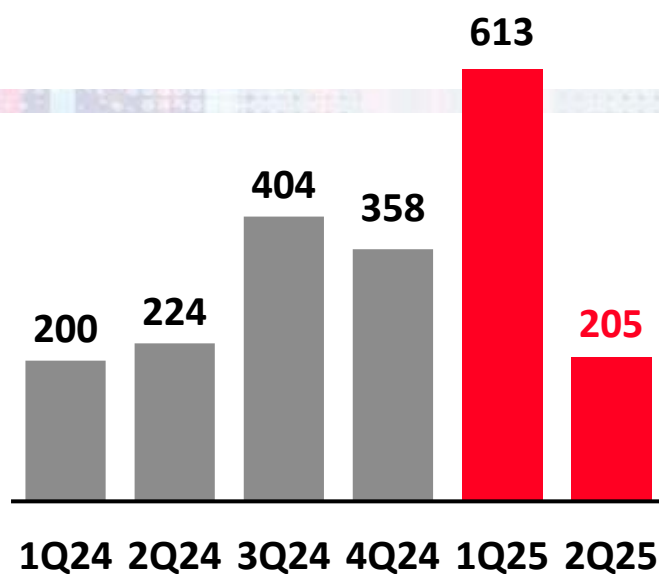
YoY	82%	191%	84%	40%	37%	-12%	5%	-18%
MoM	47%	36%	-20%	-9%	-26%	-23%	66%	-18%

Profitability Trend

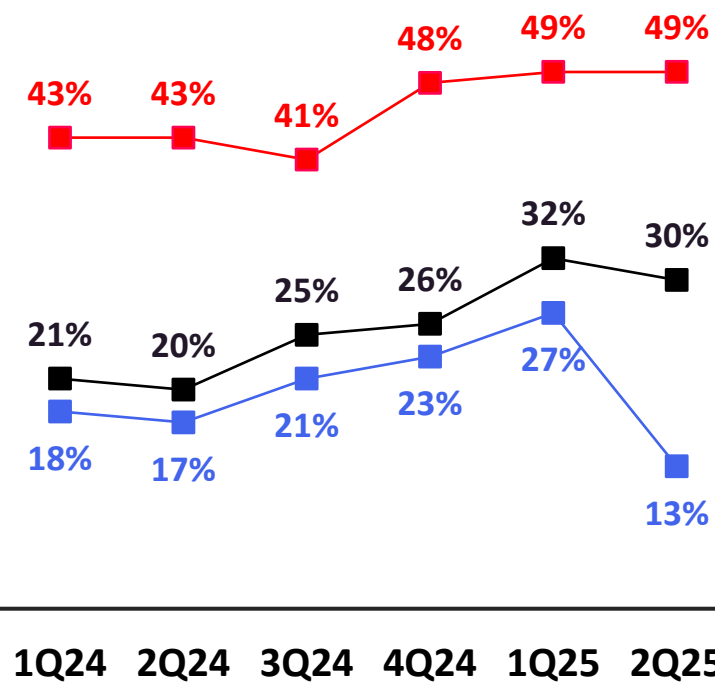
EPS

5.81	6.52	11.75	10.23	17.21	5.76
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NET INCOME (NTD M)



— Gross Margin — Operating Margin — Net Margin



Revenue by Product Mix

(1H 2025)

Probe Card

35%

Contact Element

10%

Others

4%

Coaxial Socket

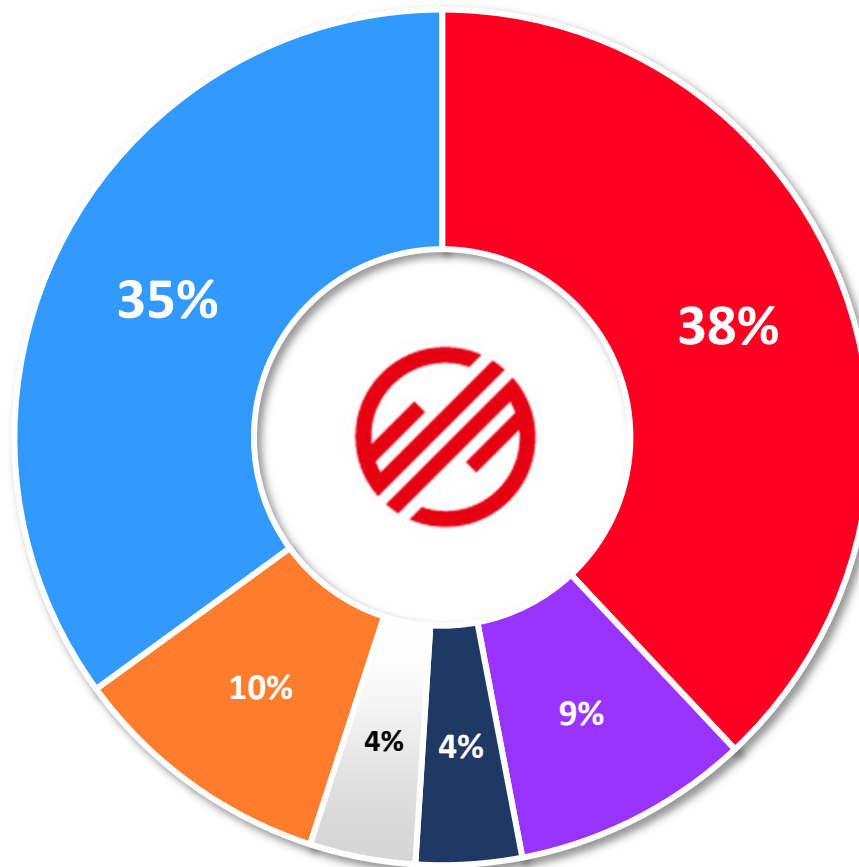
38%

RF & Plastic Socket

9%

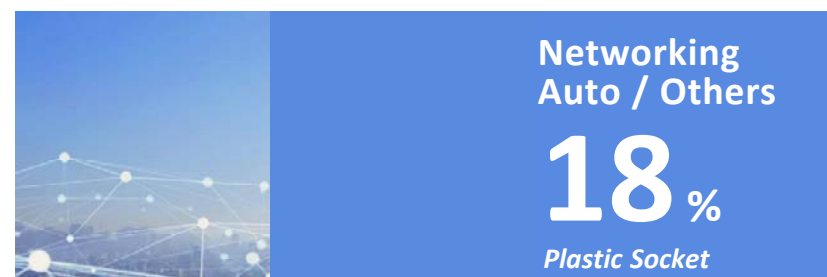
Burn-in Socket

4%



Revenue by End Market

(1H 2025)

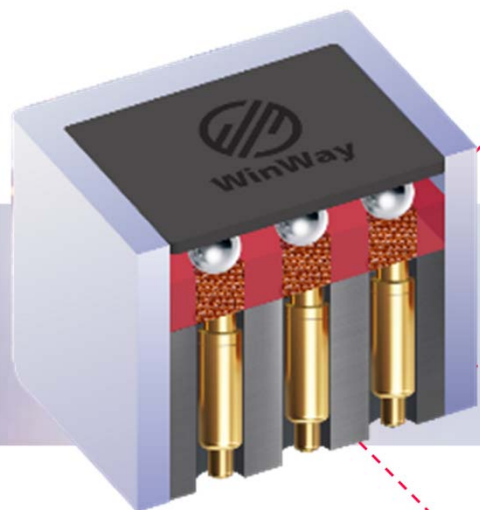




R&D Innovation

Innovative Semiconductor Test Interface Solution

WinWay HyperSocket™



2.5D / 3D / CoWoS / CPO



Generative / Agentic / Physical AI



Collaborative Robots

Patent NO.

- TWI862047 • TWI884802
- TWI862191 • CN20570508U

Patent Pending

- USA • Malaysia

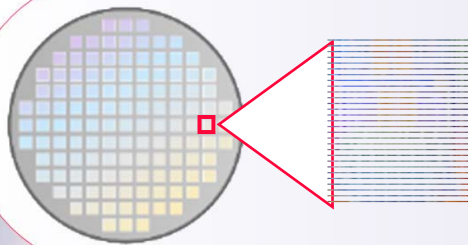
Co-Packaged Optics Test Solution

Wafer Level

Die Level

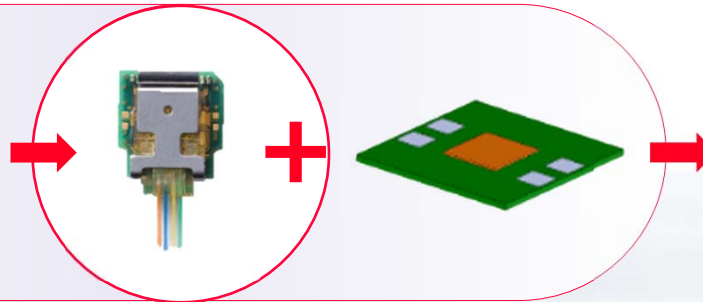
Package Level

Module Level



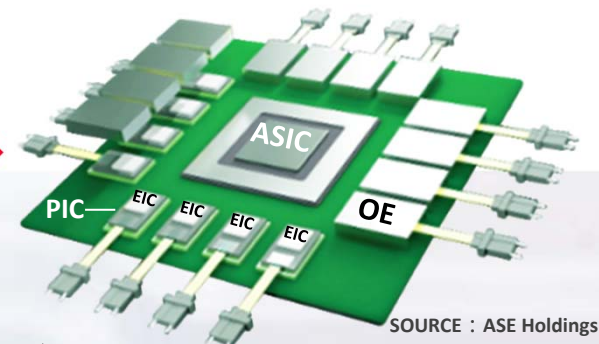
Silicon Photonic Wafer

Die



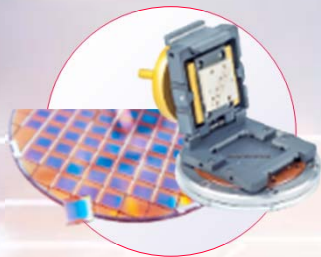
Optical Engine

CPO Substrate

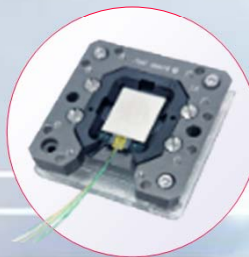


CPO Module

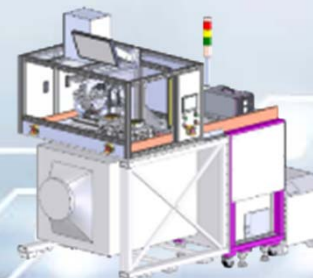
SOURCE : ASE Holdings



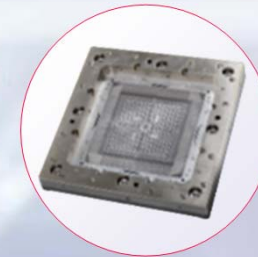
WLCSP Fine Pitch Socket
(PIC & EIC Wafer test)



Optical and Electrical Test Socket
(Optical Engine)



Double Sided Probing System

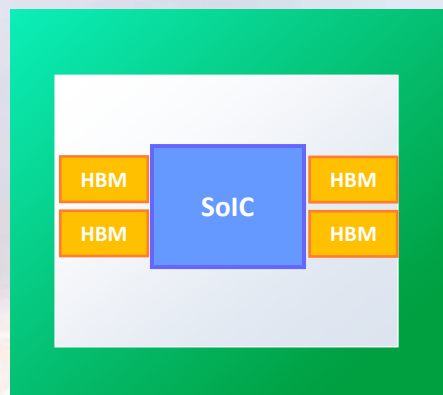


Coaxial Socket

High Power Thermal Solution

E-Flux6.0 3500W
Liquid Cooling System

2000W @100℃



3500W @100℃



Q&A





**THANK
YOU**

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